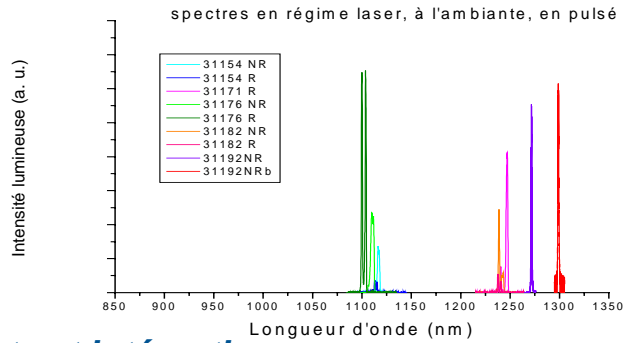
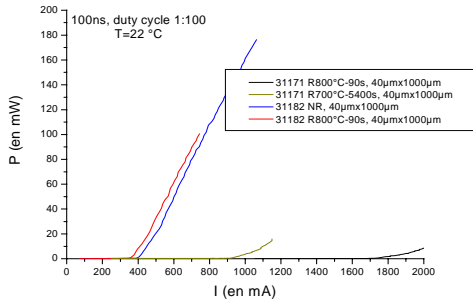


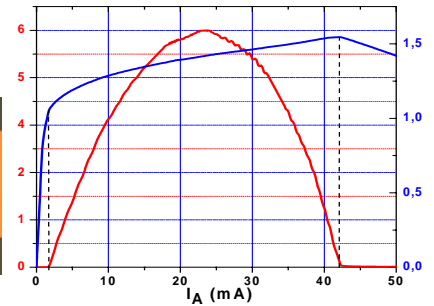
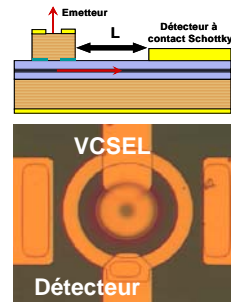
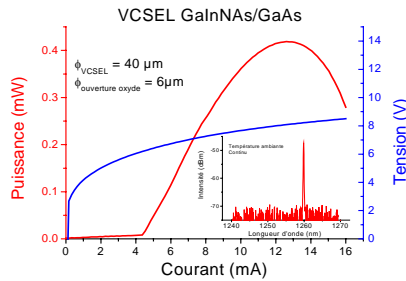
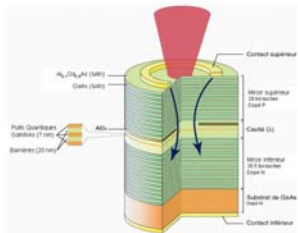
Matériau

Etude de l'épitaxie du GaInAsN sur GaAs pour emission 1,3µm



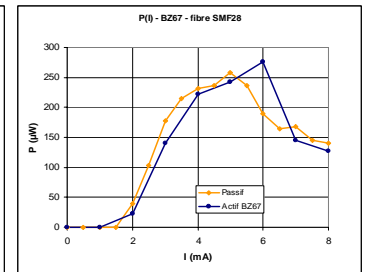
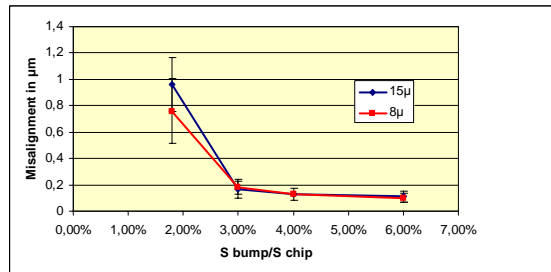
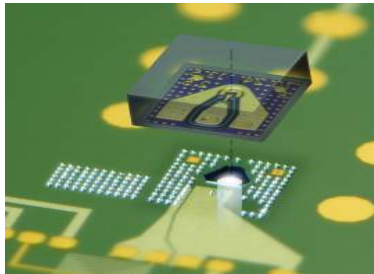
Composants et intégration

Fabrication de VCSEL 1,31µm et de VCSEL et monitoring intégré



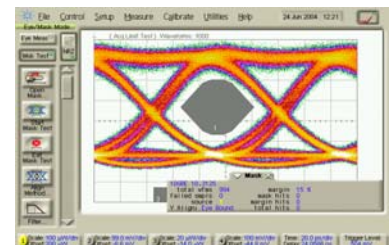
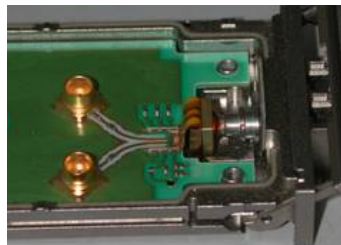
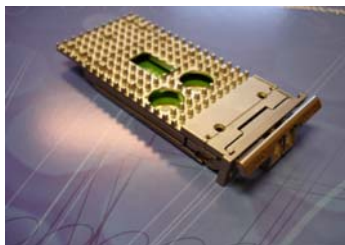
Micropackaging

Flip Chip autoaligné 0,1µm



Microsystème 10Gb/s

Intégration en wafer level packaging VCSEL/driver à 10Gb/s



Intexys (Régis Hamelin), Infineon (François Léger), LAAS (Chantal Fontaine), LETI (Philippe Grosse)

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